YOUR ULTIMATE CHOICE

FOR SOLDER

Valuable Solutions and Services

Company Profile

Founded in 1973, **SHENMAO** Technology Inc. offers total solutions of solder materials to customers by meeting and exceeding their quality and reliability requirements with products and service satisfaction accumulated over four decades of research and development experience. **SHENMAO** works closely with customers to develop new application nanotechnology product for the electronics and other industries. From production to shipment, strictly controlling each step, **SHENMAO** uses only ultra-pure virgin raw materials to produce high-quality products. Through continuous improvement, cost reduction, swift sales and service, **SHENMAO** works hard to help customers remain competitive, creating a win-win situation. **SHENMAO** Technology Inc., as the third largest Solder Materials provider, produces and markets SMT Solder Paste, Semiconductor Packaging Solder Spheres, Wafer Bumping Solder Paste, Dipping Flux, Wave Solder Bar, Solder Wire, Flux and Solder Preforms distributed from 10 worldwide locations, as the strategic manufacturing partner of leading OSATs, the 2017 top 12 of 13 largest EMS Companies and OEMs. **SHENMAO** Technology Inc. strives to offer the best quality without compromising cost and time-to-market while providing maximum value to all customers, always through superior customer service and technical support. Customer satisfaction and sustainable high quality are always **SHENMAO**'s priority.

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14 Flux for Semiconductor Packaging

16 Liquid Flux

18 Solder Bar

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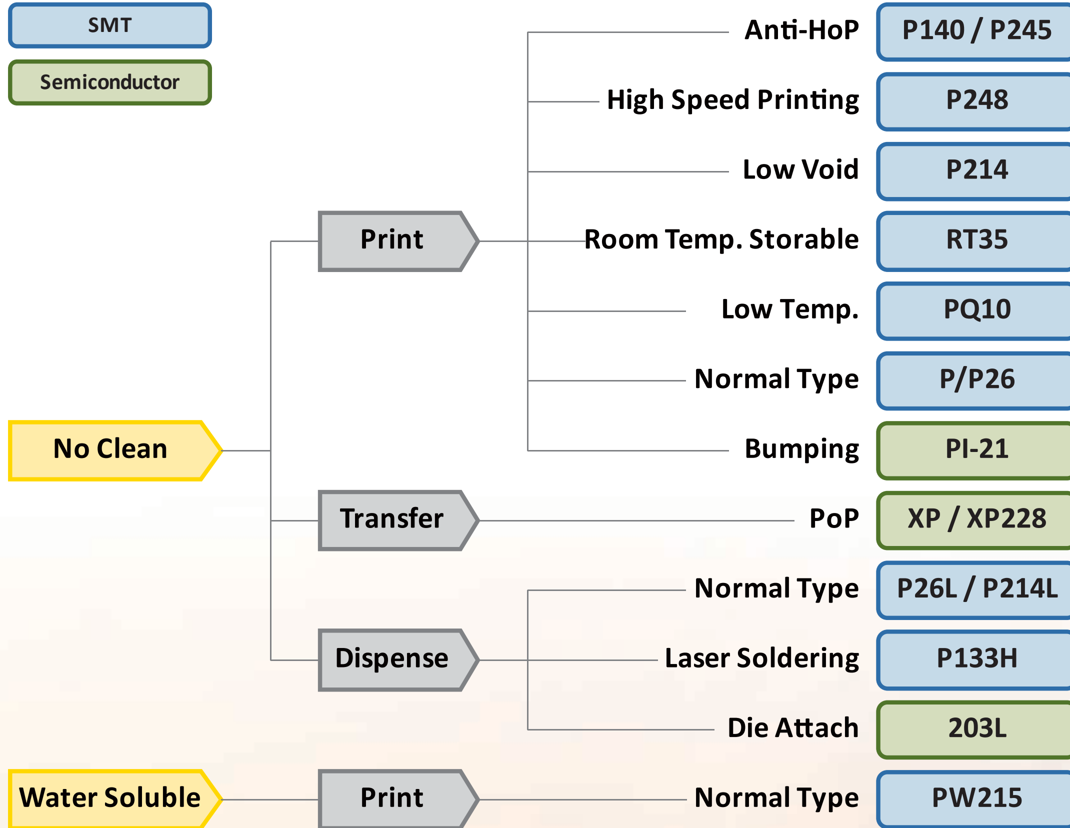
Solder Paste

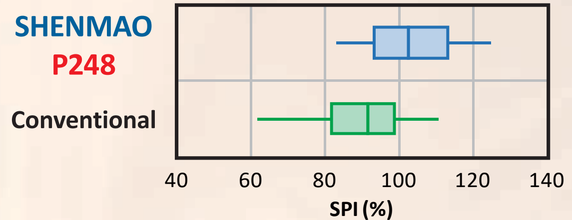
Product Guide



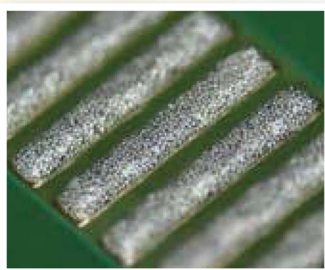
SHENMAO P248
High Speed Printing Solder Paste

- Excellent High Speed Printing
- Excellent Voiding Prevention
- Nitrogen Atmosphrere Reflow

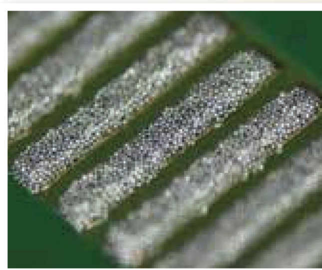
Solder Deposition



Appearance after Printing

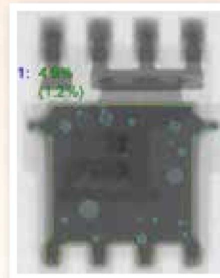


SHENMAO P248

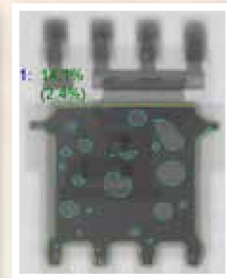


Conventional

Voiding



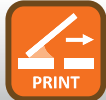
SHENMAO P248



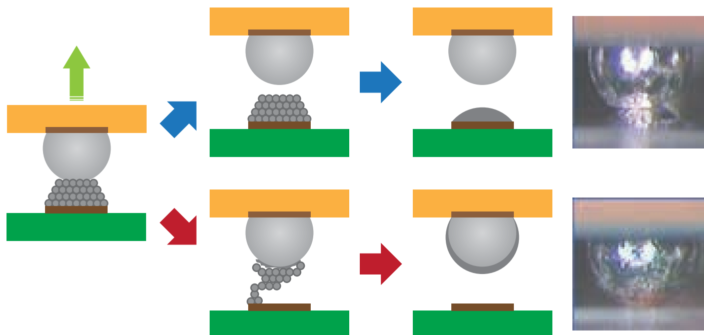
Conventional

SHENMAO P245
Anti-NWO/HoP, Halogen-free Solder Paste

SHENMAO P140
Anti-NWO/HoP, Halide Solder Paste



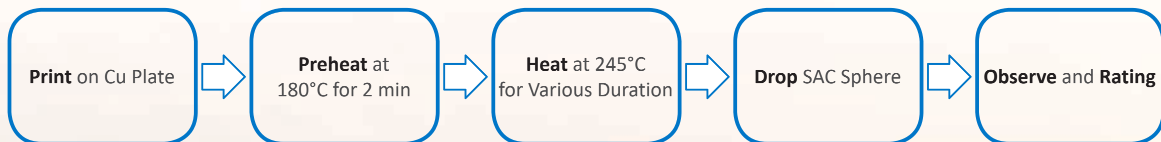
- **SHENMAO P245**: ROL0, Zero Halogen
- **SHENMAO P140**: ROL1



Root Cause of HoP
- Oxidation of Solder Sphere and Powder
- Flux Slumps during Reflow

Root Cause of NWO
- Non-wetting between Flux and Pad
- Low Tackiness Force at High Temperature

Anti-HoP Test



Standard	Class A	Class B	Class C	Class D
% of BGA Melted	>75%	50~75%	25~50%	<25%

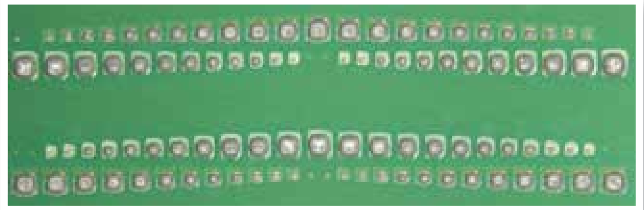
Heating Time	20s	40s	60s	80s
SHENMAO P245	Class A	Class A	Class A	Class B
SHENMAO P140	Class A	Class A	Class A	Class B
Conventional	Class A	Class B	Class C	Class D

P245 and **P140** Can Solve NWO and HoP Problems

SHENMAO PW215
Water Soluble Solder Paste

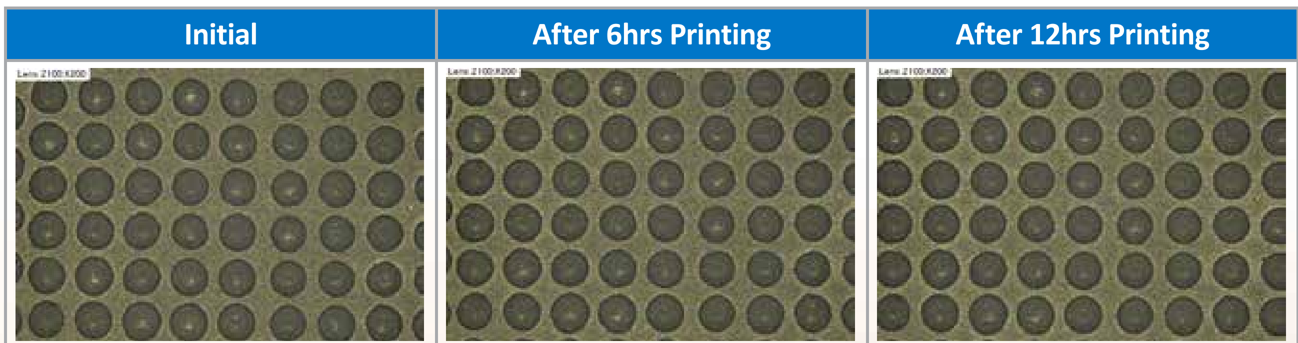
- Great Printability
- Wide Process Window

Printability (3mil~15mil)



Great Printability

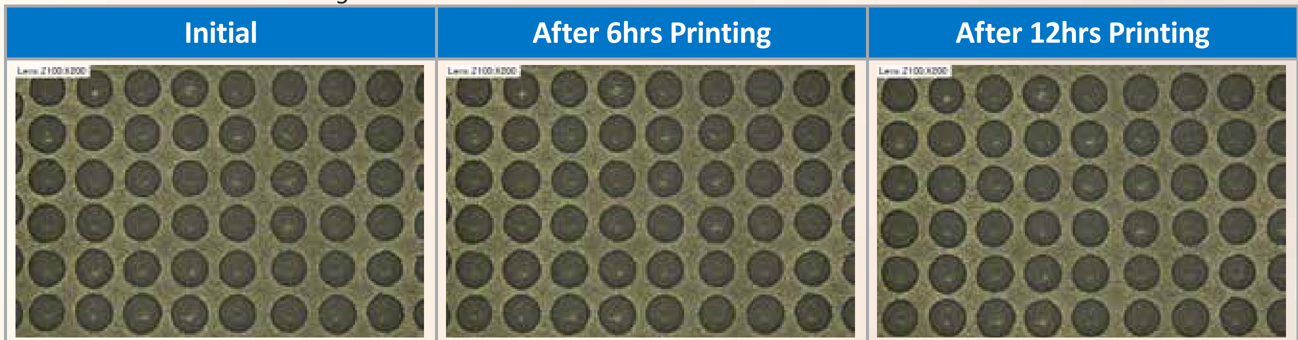
Continuous Printability



Great Deposition Remains after 12 Hours of Printing

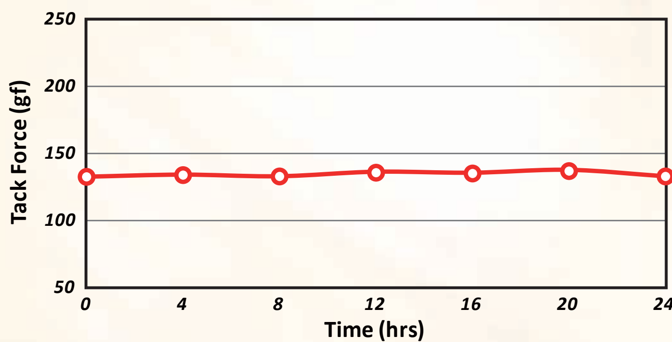
Anti-slump

6 Hours Stand Time After Printing



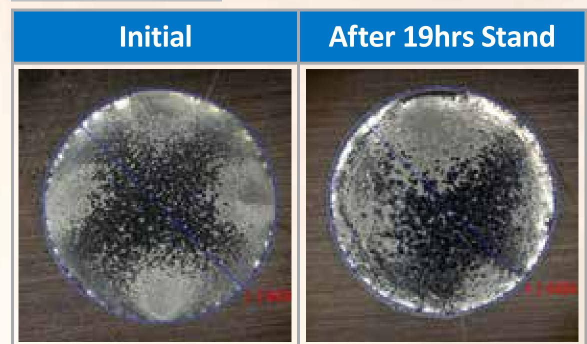
Great Anti-slump Property Remains after 6 Hours Stand

Tack Force



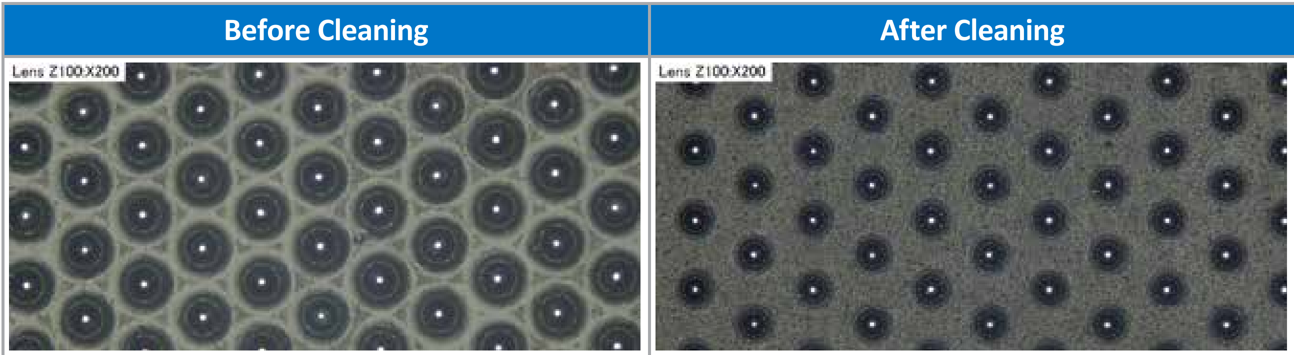
Tack Force Remains >130gf after 24 Hours Stand

Solderability



Paste Activity Remains after 19 Hours Stand

Cleanability

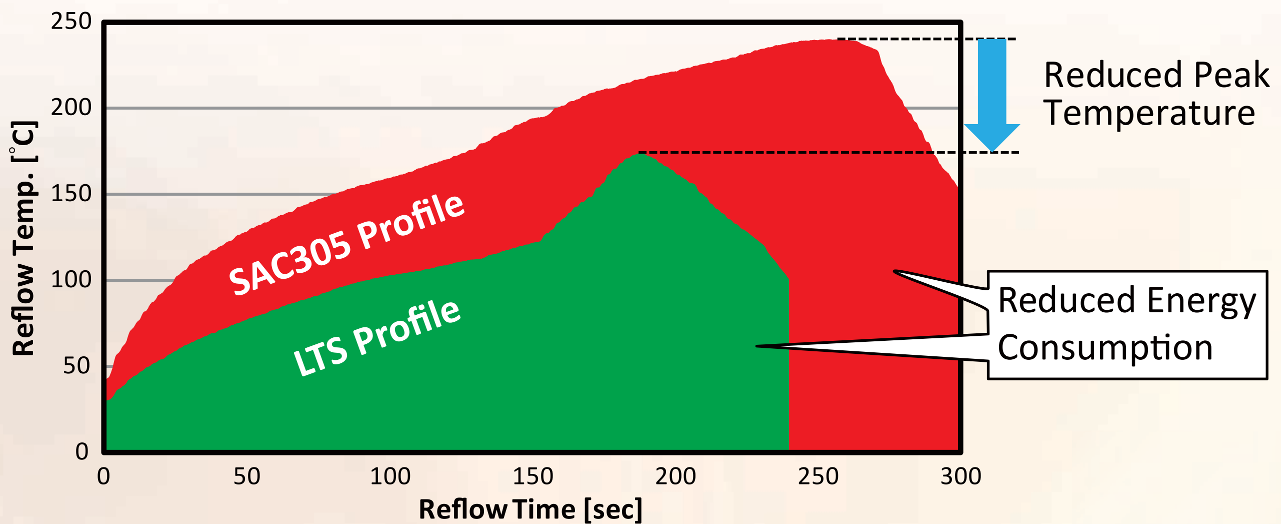


No Flux Residue after Cleaning

SHENMAO PQ10
Low Temperature Solder Paste

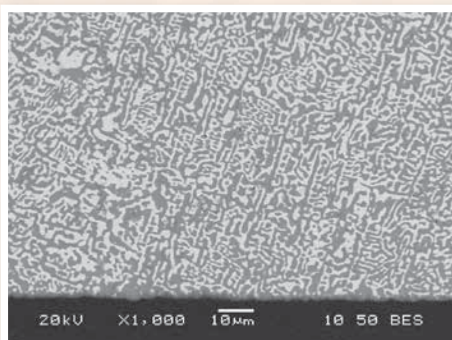
Comparison with SnAgCu

- Reduced Peak Reflow Temperature
- Reduced Energy Consumption
- Reduced Warpage of PCB and Components

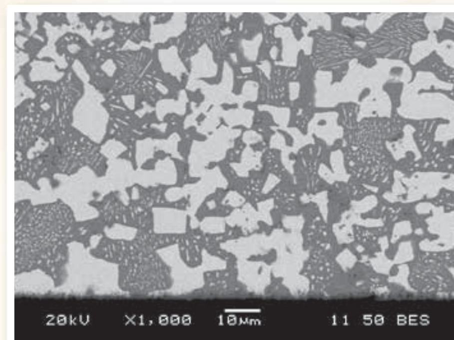


Comparison with Other Low Temperature Alloy

- Finer Bismuth Phase
- Better Drop Test Performance
- Better Thermal Cycle Test Performance



SHENMAO PQ10

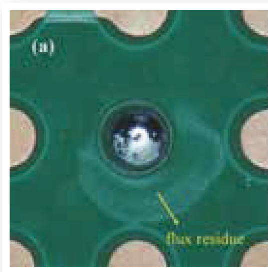


Other Sn-Bi Alloy

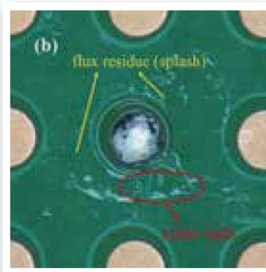
SHENMAO P133H
Laser Soldering Paste

- Applicable for Small SMD Components, Heat Sensitive Electronic Parts and Rework of BGA Components.
- Eliminated Warpage since No Laser Energy is Absorbed by PCB.

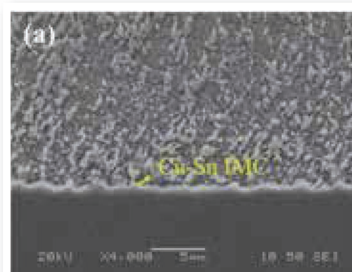
No Splash or Solder Balls

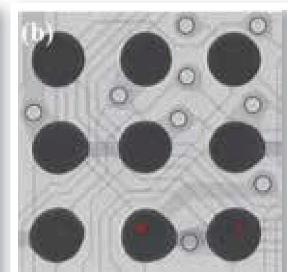


SHENMAO P133H



Conventional

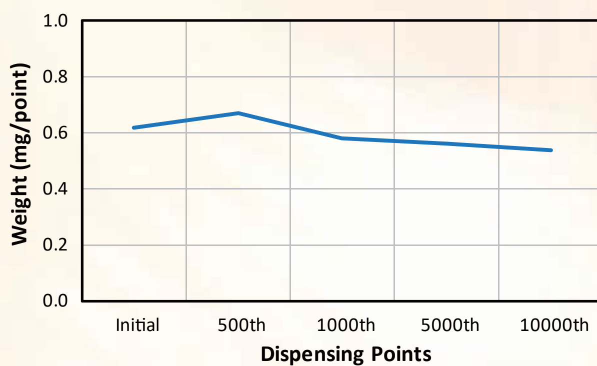




SHENMAO 203L
High-Pb Die Attach Solder Paste

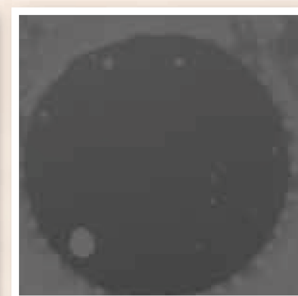
Consistent Deposition in Continuous Dispensing Process without Less or Missing Solder

Stable Dispensability on 10,000 Points



Outstanding Void Performance

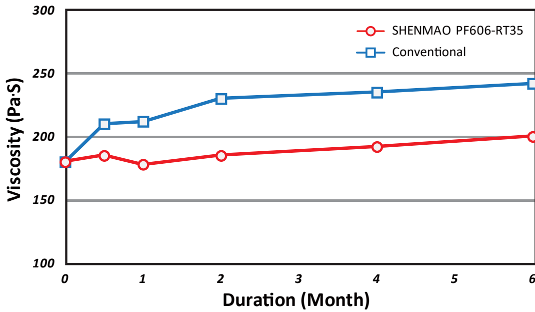
Cu Surface


Sn Surface

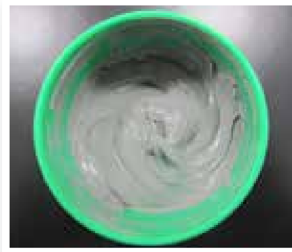
SHENMAO RT35
Room Temperature Storable Solder Paste

- No Refrigeration Required
- Storable at Room Temperature up to 35°C for Six Months

Life



Appearance



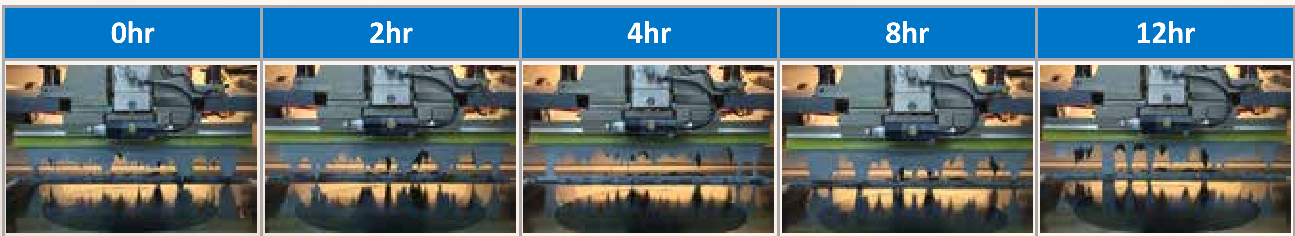
SHENMAO RT35

Conventional

SHENMAO PI-21
Bumping Paste

Printability

0hr	2hr	4hr	8hr	12hr

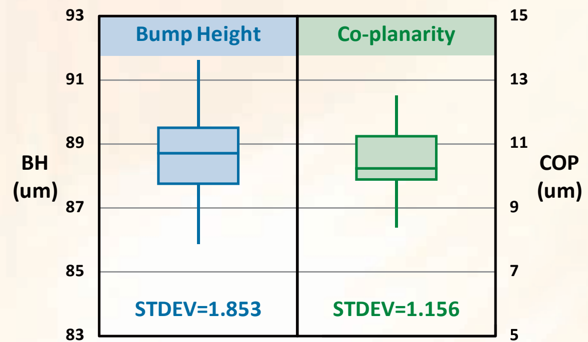


Voids

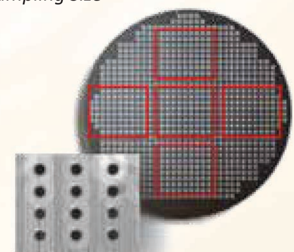
Wafer Type		Dummy
Paste		SHENMAO
Dry Film Opening (um)		150
Sampling Size		7500
FV Bump Void	>30%	0
	26~30%	4
	21~25%	10
	16~20%	16
	11~15%	9
Void Amount		39
Void Rate		0.52%

Bump Height & Co-planarity

Criteria Bump Height: 85-100um
Co-planarity: <30um



*Average of 7500 Sampling Size



Solder Wire

Product Guide

Flux	R	F4	F5	F7	F11	F13	JF3	RWB	Test Method
Flux Content	3±1%								JIS-Z-3283
Diameters	0.3~3.0mm								---
Halide Content	<0.5%	ROL0 (J-STD-004)	<0.5%	<0.5%	<1.0%	ROL0 (J-STD-004)	<1.5%	<1.0%	JIS-Z-3197
Copper Plate Corrosion Test	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS	IPC-TM-650, 2.6.15
Copper Mirror Test	PASS	PASS	PASS	PASS	PASS	PASS	---	PASS	IPC-TM-650, 2.3.32
Surface Insulation Resistance Test	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS	IPC-TM-650, 2.6.3.3
Electrochemical Migration Test	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS	IPC-TM-650, 2.6.14.1
Alloy	Compatible for all **SHENMAO** Lead-free Alloys								---
Remark	HP Approval	Halide-free, HP Approval	---	---	---	Halide-free	High Temp. Welding	---	---

Fuming Improvement

Reduce Smoke to Increase Operability and Enviromental Protection

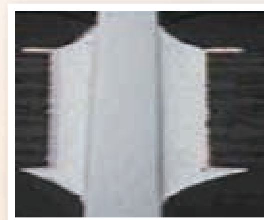
Evaluation Method

After 3 Seconds of Soldering at 380°C

Flux Residue

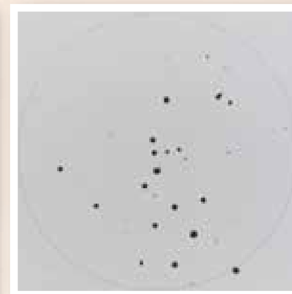
Soft Residues with Light Color after Soldering

Cross Section after Wire Soldering



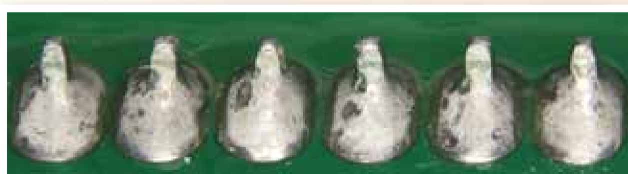
Lower Spattering

Improvement



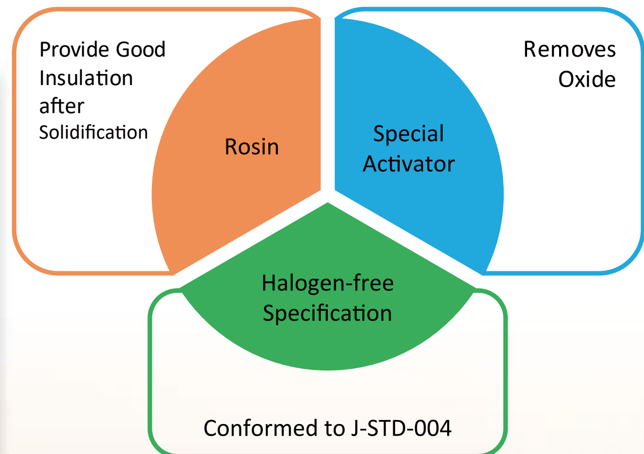
Conventional

Good Wettability



SHENMAO F13
Solder Wire for Automatic Soldering Machine

- Conformed to J-STD-004 (ROL0)
- Improved Work Environment
- Reduced the Technical Requirements
- Enhanced High Precision Soldering
- Stable and Extreme Soldering Quality
- Enhanced Soldering Efficiency
- Designed for Mass Production

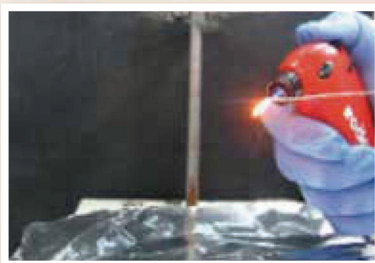


SHENMAO JF3
Air-con. Brass Flame Welding Solder Wire

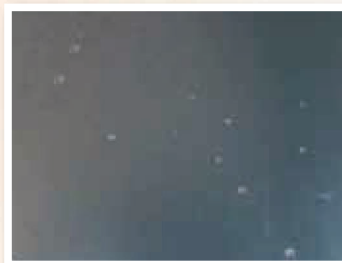
- Good Thermal Endurance
- Good Solderability
- Less Smoke
- Low Spatter
- Good Reliability

Spattering Test

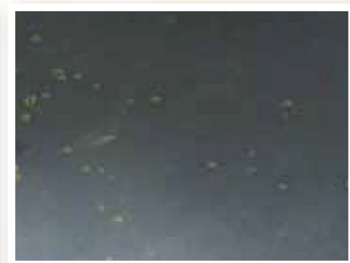
Direct Heating Solder Wire under 800°C



Heating Method



SHENMAO JF3



Conventional

Solder Sphere

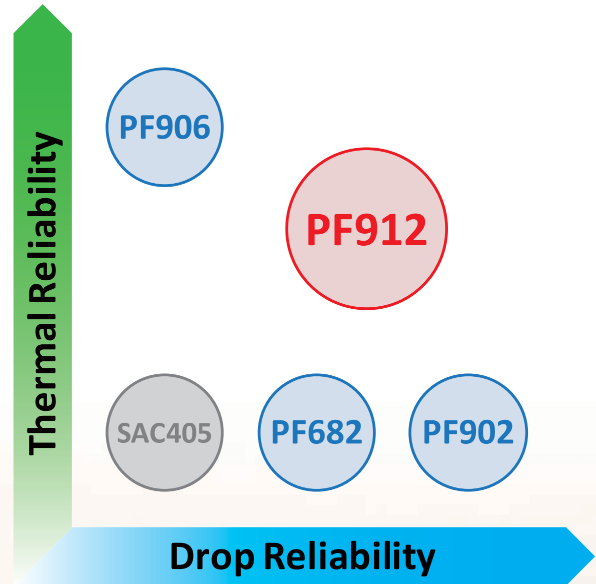
Solder Spheres with Various Alloy Compositions and Diameters

Alloy Series	Composition	
Sn-Ag-Cu	PF683	Sn-1Ag-0.5Cu
	PF684	Sn-3Ag-0.5Cu
	PF685	Sn-4Ag-0.5Cu
↑ Drop Reliability	PF682	Sn-1.2Ag-0.5Cu+Ni
↑ Thermal Reliability	PF906	Sn-4Ag-0.5Cu+Bi
New Improvement ↑ Drop/Thermal Reliability	PF912	Sn-2Ag-0.5Cu+Bi

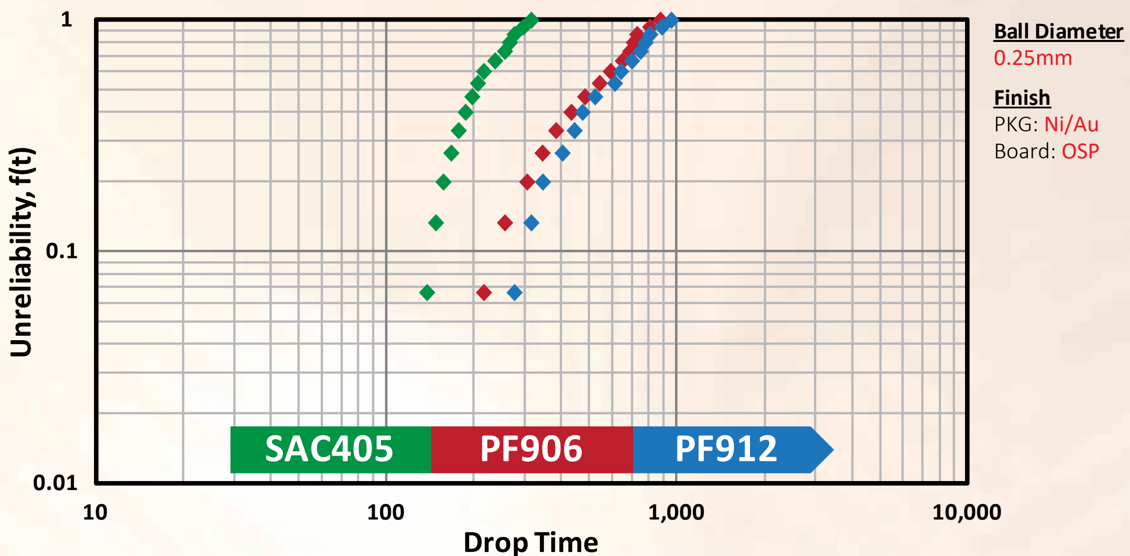
Level	Diameter (µm)	Tolerances (µm)
Solder Sphere	500~760	±20
	300~490	±10
	100~290	±5
Micro Solder Sphere	45~95	±3

SHENMAO Micro Solder Sphere 40µm Diameter are in Development

Product Guide

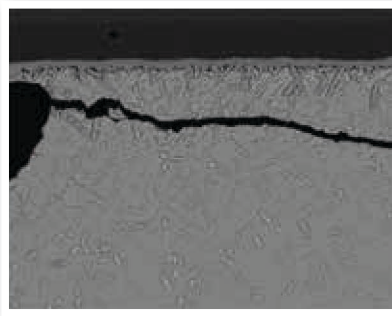


Board Level Drop Test



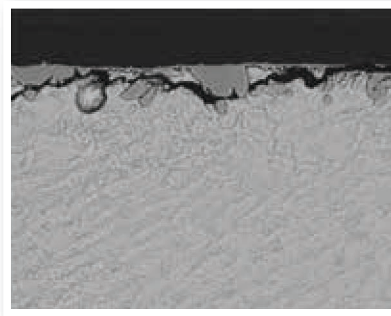
SHENMAO PF912

Crack within Solder



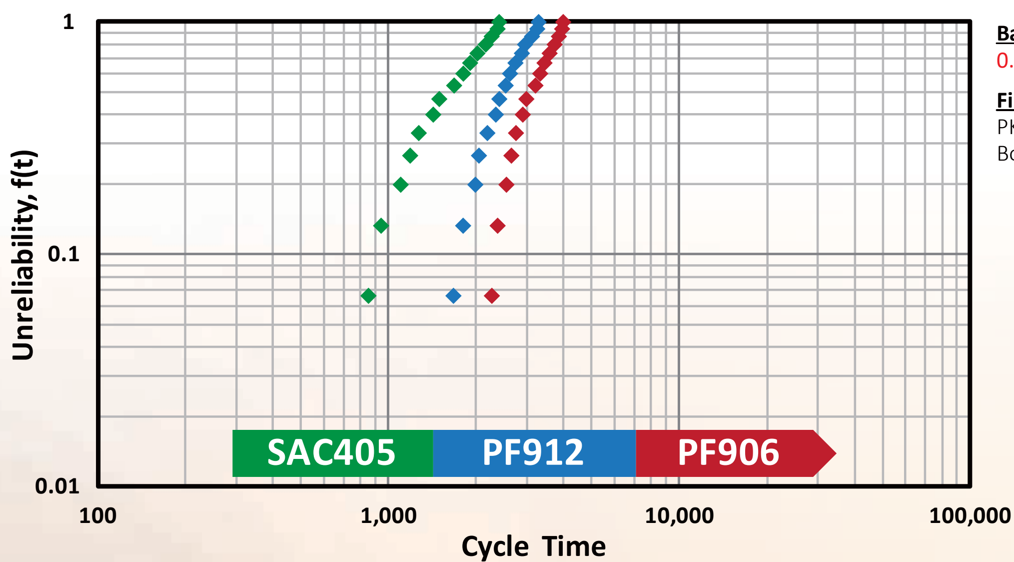
SAC405

Crack along Interface



SHENMAO PF912 Alloy Exhibits Highly Improved Mechanical Shock Reliability.

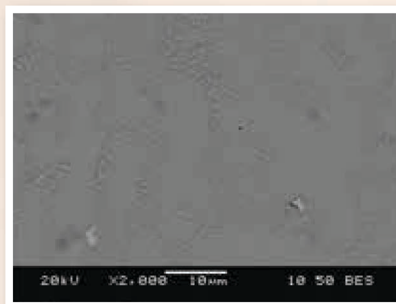
Board Level Thermal Cycle Test



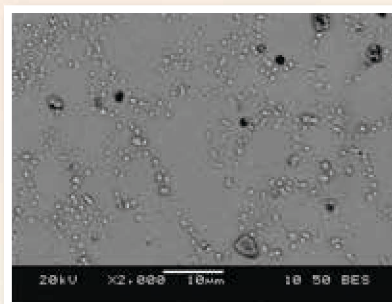
Ball Diameter
0.25mm

Finish
PKG: Ni/Au
Board: OSP

SHENMAO PF906 Initial

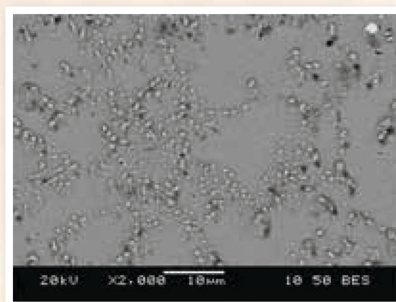


SHENMAO PF906 After TCT

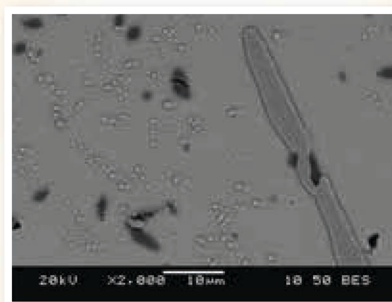


Finer Ag_3Sn

SAC405 Initial



SAC405 After TCT



SHENMAO PF906 Alloy Exhibits Highly Improved Thermal Shock Reliability.

Solder Preform

Solder Preforms in Various Alloys and Forms

Regular Solder Preforms

The precise dimensions of solder preforms ensure customers control of the increment solder volume accurately, hence increasing component reliability and solder joint strength.

Sheetlike Solder Preforms

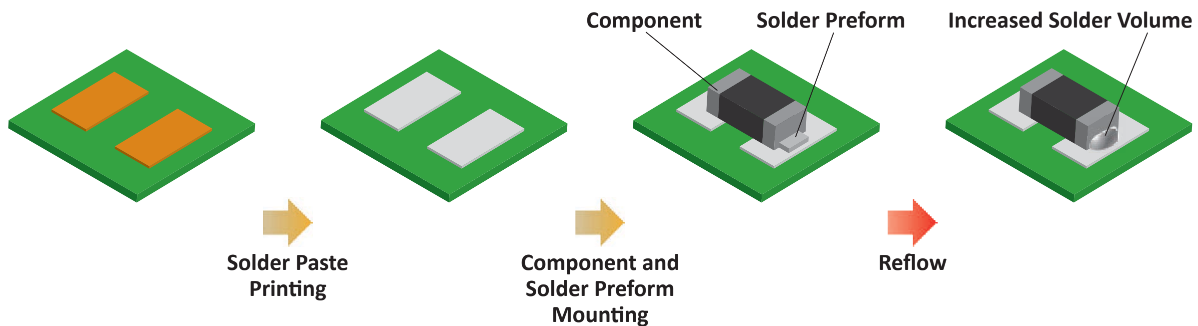
The surface flatness and thickness homogeneity of sheet-like solder preforms ensures high yield rates and stability in the IC packaging process, especially in die attachment.

Customized Solder Preforms

The preforms can be manufactured in various solder alloys and forms to fulfill different application requirements.

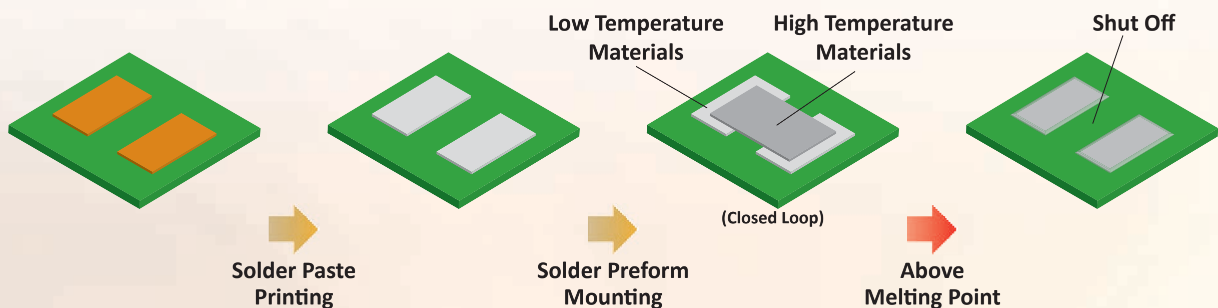
Application 1

Solder preforms increase the solder volume of solder joints to provide better solder joint appearance, decrease voids, and increase mechanical strength.



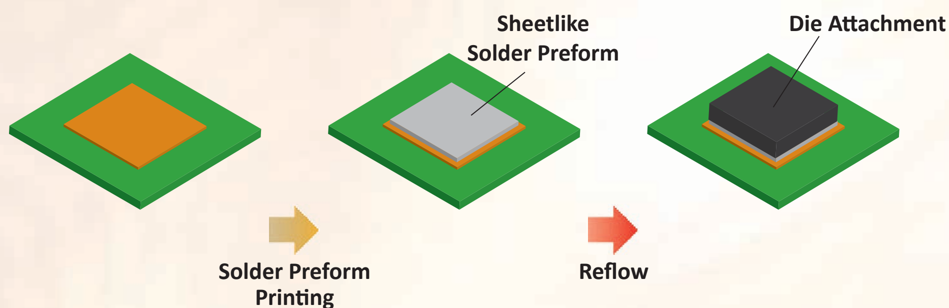
Application 2

Solder preforms can serve as a fuse. The circuit will shut off when the temperature reaches the low melting point of the alloy and disconnects the two pads soldered in between.



Application 3

For semiconductor packaging, the surface flatness and thickness homogeneity of preforms enable uniform heating and connection to adjacent surfaces.



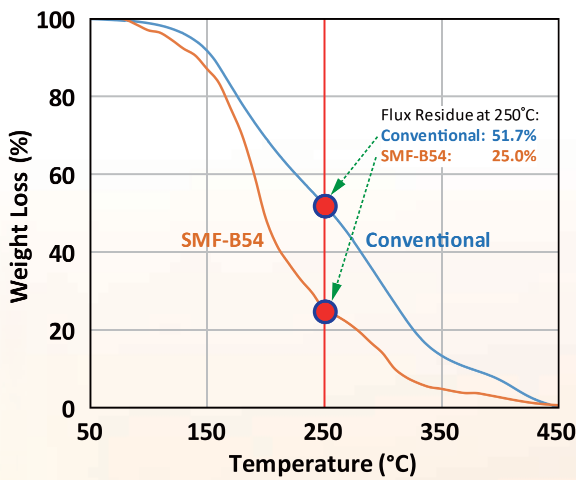
Flux for Semiconductor Packaging

SHENMAO SMF-B54
Low Residue Flip-chip Flux

- Designed for Flip-chip Dipping Applications
- Applicable for Fine-pitch Design
- Compatible with Underfills
- Low Residue

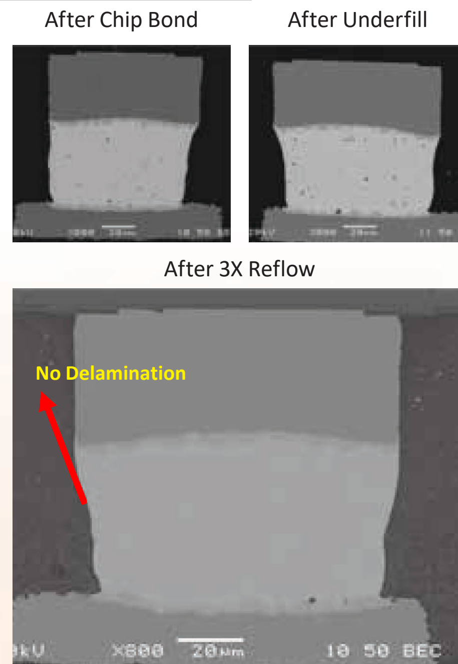
Flux Residue - TGA Analysis

**Condition: 40-450°C, 10°C/min*

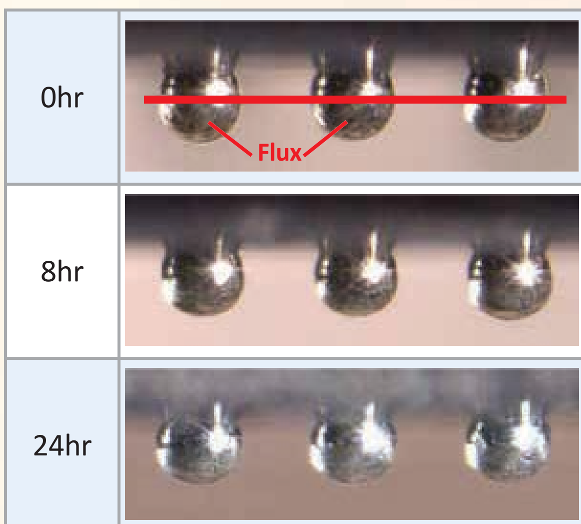


- Less Residue
- No Cleaning Needed by Eliminated Clean Requirement

Compatibility Test

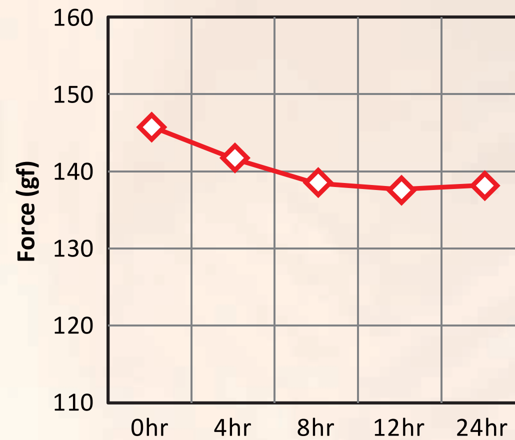


Dipping Performance



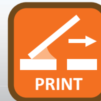
Good Characteristic in Flux Dipping Stability

Tacky Force

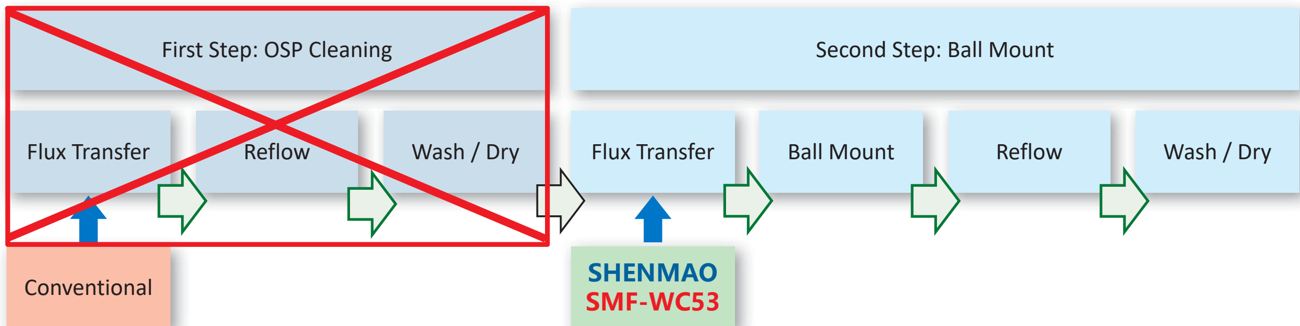


High and Stable Tackiness

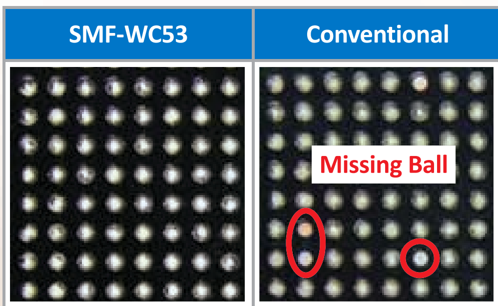
SHENMAO SMF-WC53
Cu-OSP Pad Ball Attach Flux



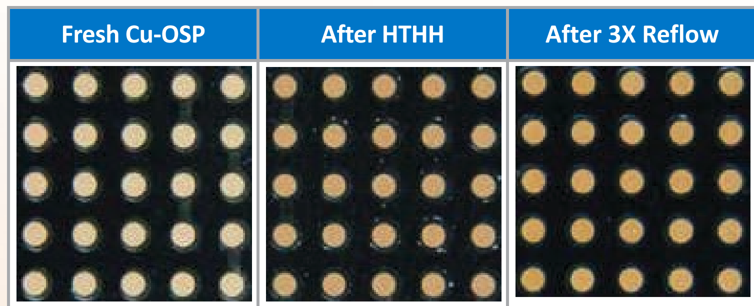
- Applicable for Printing or Pin Transfer
- Eliminated for OSP Pre-clean Process
- Excellent Cleanability



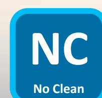
Solderability
Pad Condition: After 85°C/85%RH 240hrs



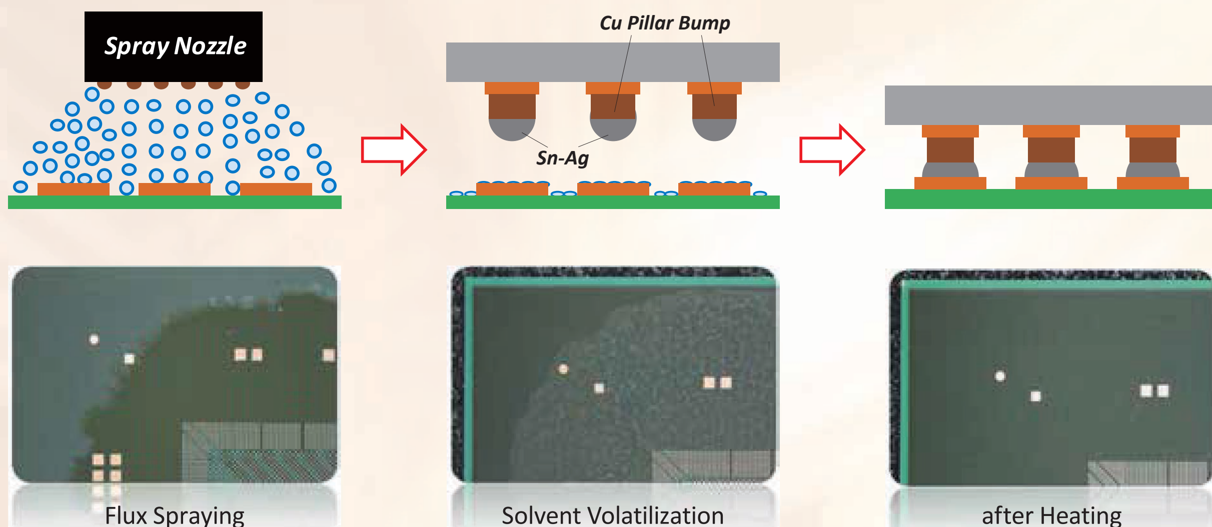
Cleanability
HTHH: High Temp. High Humidity (85°C/85%RH for 240hrs)
Reflow: Peak Temp.240°C



SHENMAO SMF-UL51-D
Ultra Low Residue Spraying Flux



- Designed for Copper Pillar Bonding
- Superior Spraying Uniformity and Outstanding Soldering Performance with Ultra Low Flux Residue



Flux Spraying | Solvent Volatilization | after Heating

Liquid Flux

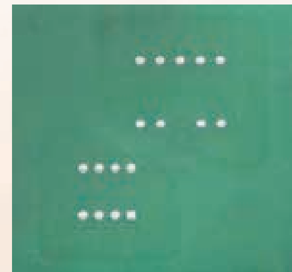
Product Guide

Flux	Solid Content (%)	Specific Gravity (25°C)	Acid Value (mg KOH/g)	Flux Type
SM-717	4.9±0.8	0.803±0.015	26.0 ± 6.0	ROL1
SM-727	5.8±0.7	0.807±0.015	37.0 ± 8.0	ROL0
SM-816	3.4±0.5	0.806±0.012	20.0 ± 5.0	ROL1
SM-816-V	4.2±0.7	0.800±0.015	23.0 ± 6.0	ROL1
SM-818	3.6±0.7	0.795±0.012	18.0 ± 7.0	Cl: <900 ppm Br: <900 ppm Cl+Br: <1500 ppm
SM-819	4.1±0.6	0.798 ± 0.01	21.0 ± 6.0	
SM-827	7.0±0.9	0.807±0.012	28.0 ± 6.5	
SM-857	5.5±0.6	0.805±0.012	28.5 ± 7.0	ROL1
SM-862	5.3±0.6	0.796±0.012	27.0 ± 6.0	ROL0
SM-863	3.0±0.5	0.796±0.012	21.0 ± 5.0	ROL0

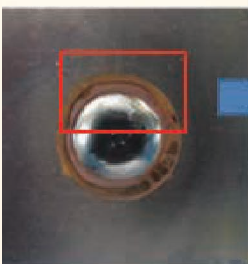
Surface Insulation Resistance Test

No Electromigration Occurs

Low Residue

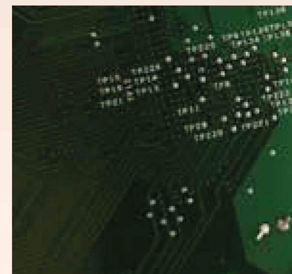


Copper Plate Corrosion Test



No Corrosion after 10 Days of Being Exposed to Humidity

Solderability



SHENMAO SM-901W
Water-based Liquid Flux

Specification

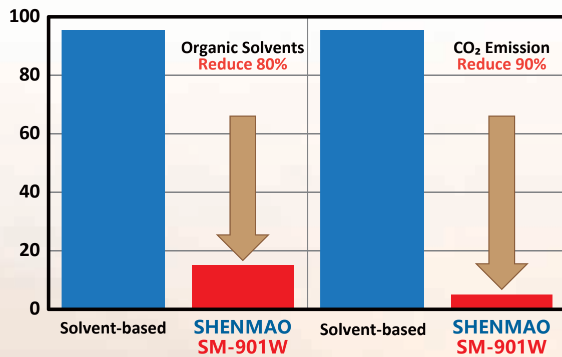
Flux	Solid Content (%)	Specific Gravity (25°C)	Acid Value (mg KOH/g)
SM-901W	5.5 ± 0.7	1.020 ± 0.020	40.0 ± 5.0

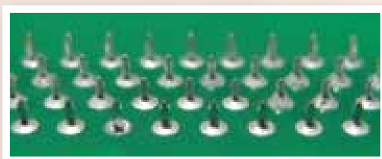
Advantages

- Reduced Cost
    - Reduced Transport Cost
    - Reduced Storage Cost
- Safety
    - No Toxic Substance
    - Easier Waste Disposal

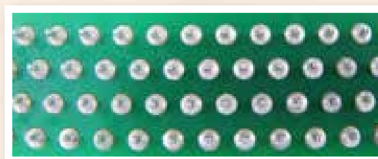
SHENMAO SM-901W

Solvent-based

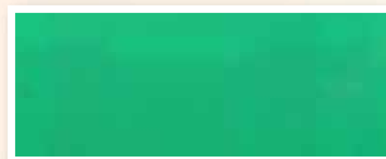




Excellent Solderability



No Bridge



No Residue

Solder Bar

Anti-copper Erosion Solder Bar

Higher copper erosion resistance solder material is needed to prevent the breaking of thin wire during dipping process.

Products List

Product Series	Alloy	Composition	Dipping Temperature
UHT-CR Series	**PF731**	Sn-3Cu-0.2Ni-X	390~500°C
	PF732	Sn-5Cu-0.2Ni-X	

Low Dross

Reduce Solder Material Usage
Better Operability

Reduce over 40%

Anti-oxidation

Bright and Clean Liquid Surface
Excellent Dipping and Soldering Performance

SHENMAO Anti-copper Erosion Solder Alloys

High Cu-erosion Resistance

Prevent Breaking Problem of Thin Cu Wire
Increase Operation Time

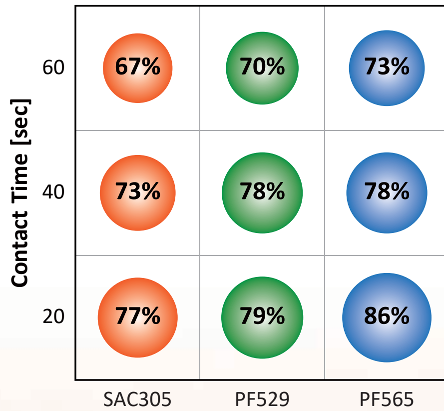
Conventional 275% Better

UHT-CR

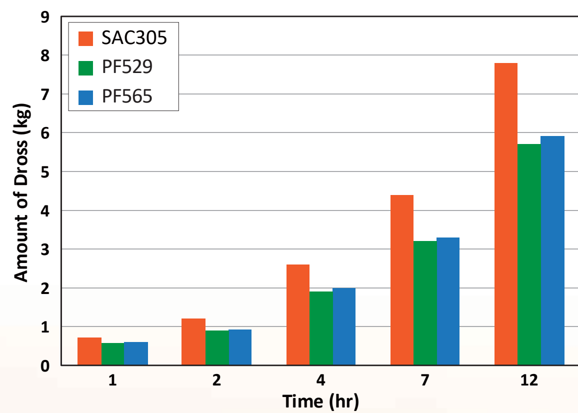
Low-Ag High Performance Solder Bar

Conventional High-Ag Product	Shenmao Low-Ag High Performance Product	
SAC305	**PF529** Sn-0.3Ag-0.7Cu-X	**PF565** Sn-0.05Ag-0.7Cu-X
Good Properties High Cost	Improved Anti-copper Erosion Performance by Adding Ni Element Lowered Dross Rate by Adding Ge Element	

Copper Erosion Prevention



Reduced Dross



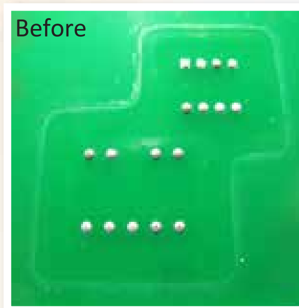
Cleaner

Product Guide

Cleaner		SMC-11	SMC-12
Specific Gravity (25°C)		0.755±0.09	0.741±0.09
Halogen Content		Halogen-free	Halogen-free
Applicable Object	Liquid Flux		●
	Solder Wire	●	
	Solder Paste	●	
	Stencil, Chain, Fixture	●	

Application

Stencil Cleaning (**SMC-11**)



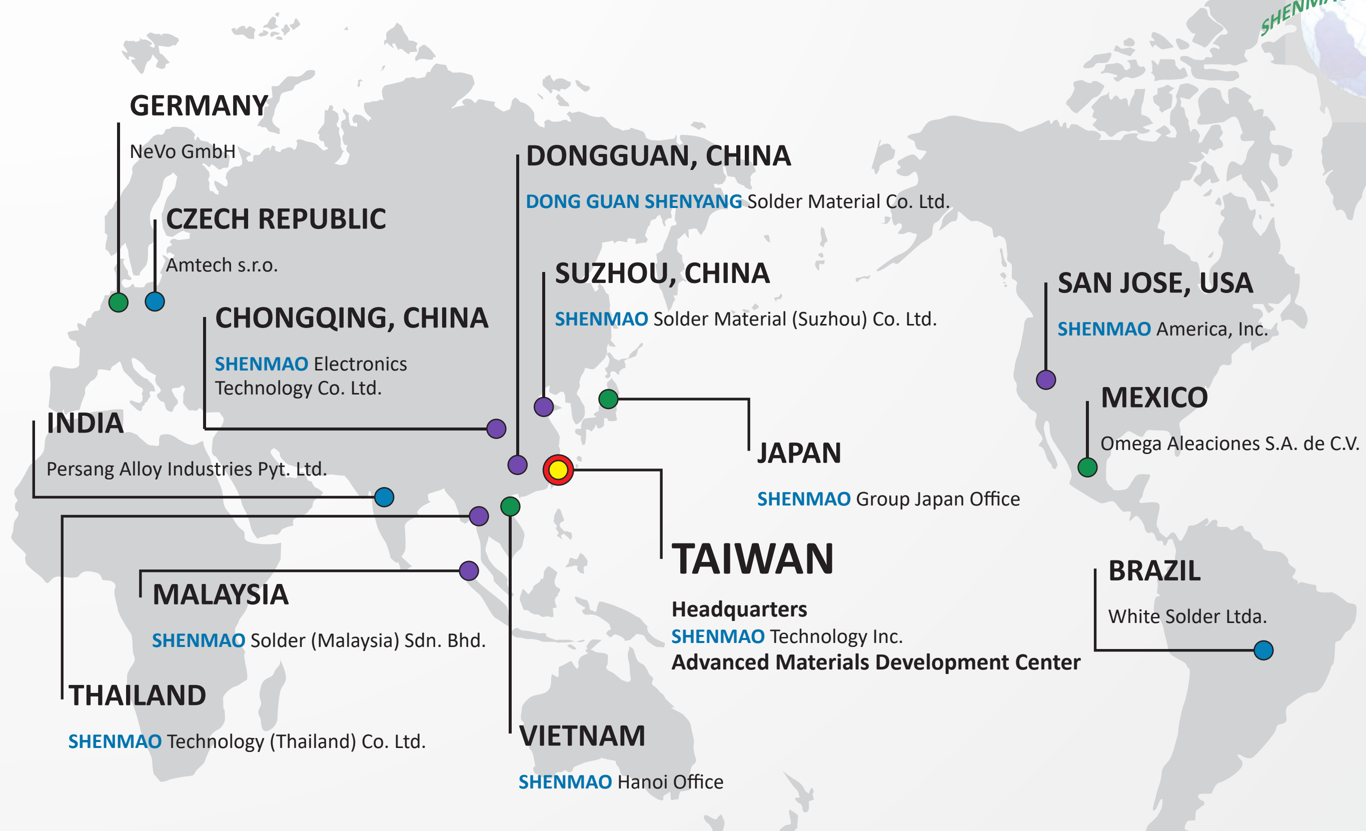
Flux Residue Cleaning (**SMC-12**)

Main SHENMAO Alloys

Alloy	Composition	Melting Point (°C)	Forms			
			Bar	Wire	Paste	Preform
SnAgCu Series						
PF606	Sn-3Ag-0.5Cu-X	217~219	●	●	●	●
PF629	Sn-0.3Ag-0.7Cu	217~226	●	●	●	●
PF632	Sn-1Ag-0.5Cu	217~226	●	-	●	●
SnCu Series						
PF604	Sn-0.7Cu	227~228	●	●	●	●
PF643	Sn-0.7Cu-0.04Ni	227~228	●	●	-	●
PF565	Sn-0.05Ag-0.7Cu-X	227~228	●	-	●	●
PF731	Sn-3Cu-0.2Ni-X	227~340	●	-	-	-
PF732	Sn-5Cu-0.2Ni-X	227~370	●	-	-	-
SnAg Series						
PF616	Sn-4Ag	221~225	●	-	●	●
Pure Sn Series						
PF605	Sn99.99	232	●	-	●	●
Lead Containing Series						
SH63	Sn-37Pb	183	●	●	●	●
SH62	Sn-36Pb-2Ag	179	●	●	●	●
SH-0595	Sn-95Pb	308~312	●	●	●	●
SH-05X25	Sn-92.5Pb-2.5Ag	280~284	●	●	●	●
SH-10882	Sn-88Pb-2Ag	268~290	●	●	●	●
Low Temperature Series						
PF602	Sn-58Bi	139	●	-	●	-
PF653	Sn-57Bi-1Ag	137~142	●	-	●	-
PF676	Sn-57.6Bi-0.4Ag	137~142	●	-	●	-
PF713	Sn-17Bi-0.5Cu	184~209	-	-	●	-
PF714	Sn-35Bi-1Ag	138~187	-	-	●	-
PF734	Sn-40Bi-Ag-X	137~170	-	-	●	-
PF735	Sn-57Bi-Ag-X	137~142	●	-	●	-
PF743	Sn-48Bi-Ag-X	137~155	-	-	●	-
SnSb Series						
PF623	Sn-5Sb	238~241	●	-	●	●
PF726	Sn-10Sb	245~266	●	-	●	●

Alloy	Composition	Melting Point (°C)	Sphere
BGA Series			
PF682	Sn-1.2Ag-0.5Cu+Ni	217~227	●
PF683	Sn-1Ag-0.5Cu	217~227	●
PF684	Sn-3Ag-0.5Cu	217~219	●
PF685	Sn-4Ag-0.5Cu	217~219	●
PF687	Sn-3.5Ag	220~222	●
PF698	Sn-2.6Ag-0.6Cu	217~219	●
PF906	Sn-4Ag-0.5Cu+Bi	210~217	●
PF908	Sn	230~233	●
PF909	Sn-3Ag-0.5Cu+Bi	210~217	●
PF912	Sn-2Ag-0.5Cu+Bi	210~225	●
PF623	Sn-5Sb	238~241	●
Low Temperature BGA Series			
PF602	Sn-58Bi	139	●
PF653	Sn-57Bi-1Ag	137~142	●
PF676	Sn-57.6Bi-0.4Ag	137~142	●
PF713	Sn-17Bi-0.5Cu	184~209	●
PF714	Sn-35Bi-1Ag	138~187	●
PF734	Sn-40Bi-Ag-X	137~170	●
PF735	Sn-57Bi-Ag-X	137~142	●
PF743	Sn-48Bi-Ag-X	137~155	●

Global Directory



● Headquarter ● R&D ● Manufacturing Plant ● Office
● Collaboration Partner w/ Manufacturing Plant

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